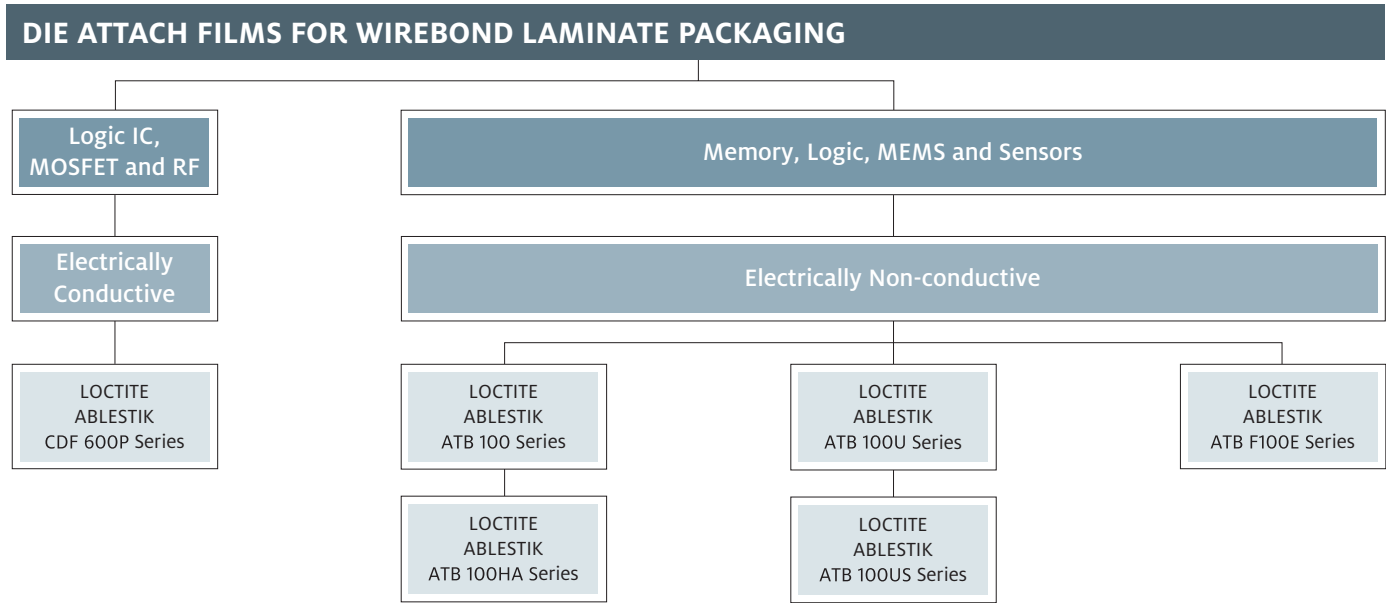




Henkel Solutions for Laminate Packaging Die Attach Films



ELECTRICALLY CONDUCTIVE DIE ATTACH FILMS (CDAF)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	FILM THICKNESS (µm)	MOISTURE SENSITIVITY LEVEL, MSL	THERMAL CONDUCTIVITY (W/m·K)	IN-PACKAGE THERMAL RESISTANCE (K/W)
LOCTITE ABLESTIK CDF 600P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Low stress and excellent wetting for large die Compatible with various metal surfaces, including solder Recommended for thin wafer handling applications Oven cure 	25	L2 260°C capable	1	2.1

ELECTRICALLY NON-CONDUCTIVE DICING DIE ATTACH FILMS (DDF)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DICING TAPE	FILM THICKNESS (µm)	WAFER THICKNESS (µm)	MOISTURE SENSITIVITY LEVEL, MSL	MODULUS AT 25°C (MPa)
LOCTITE ABLESTIK ATB 100 Series	Silica-filled, rubberized epoxy die attach adhesive	<ul style="list-style-type: none"> Compatible with Cu wire or Au wire packages Good adhesion onto low density fiberboard (LDF) Compatible with Stealth Dicing Before Grind (SDBG) process Oven cure 	Non-UV	15, 20, 25 or 30	≥ 75	L2 260°C capable	1,170
LOCTITE ABLESTIK ATB 100HA Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Consistent dicing and die pickup for large die applications Compatible with Stealth Dicing Before Grind (SDBG) process SkipCure 	UV/Non-UV	5, 10, 15, 20, 25 or 30	≥ 50	L1 260°C capable	2,299
LOCTITE ABLESTIK ATB 100U Series	Silica-filled, rubberized epoxy die attach adhesive	<ul style="list-style-type: none"> Compatible with Cu wire or Au wire packages Compatible with Stealth Dicing Before Grind (SDBG) process Fast oven cure 	Non-UV	5, 10, 15, 20, 25 or 30	≥ 75	L2 260°C capable	875
LOCTITE ABLESTIK ATB 100US Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Long thermal budget (4 hr. at 175°C) Consistent dicing and die pickup for large die applications SkipCure during molding process 	UV/Non-UV	5, 10, 15, 20, 25 or 30	≥ 50	L2 260°C capable	1,277
LOCTITE ABLESTIK ATB F100E Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Suitable for small to large die Excellent workability for below 3 mm x 3 mm die Long work life (4 months before and after lamination) Compatible with Stealth Dicing Before Grind (SDBG) process Film over wire (FoW) and film over die (FoD) applications Oven cure 	UV/Non-UV	25 FoW: 35 – 80 FoD: 90 – 150	≥ 75	L1 260°C capable	5,256

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